

**Integrated chip package structure using silicon substrate and method of
manufacturing the same**

Appl. No.	:	10/755,042	Confirmation No.	8665
Applicant	:	Mou-Shiung Lin et al.		
Filed	:	January 9, 2004		
TC/A.U.	:	2815		
Examiner	:	Fenty, Jesse A		
Docket No.	:	MEGP0004USA1		
Customer No.	:	27765		

Commissioner for Patents
P.O. Box 1450
Alexandria VA 22313-1450

AMENDMENT

5 Sir:

In response to the Office action of June 22, 2006, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

10 **Remarks/Arguments** begin on page 9 of this paper.